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INFORMATION DISCLOSURE CITATION (use as many sheets as necessary)				Application Number	10/660,926
				Filing Date	September 12, 2003
				First Named Inventor	Wen J. Meng
				Art Unit	3725
				Examiner Name	D. Suhol
Sheet	1	of	1	Attorney Docket Number	Meng 0310

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U.S. PATENT DOCUMENTS					
Exam. Initial	Document No.	Date	Name	Class	Subcl.

FOREIGN PATENT DOCUMENTS				
Exam. Initial	Foreign Patent Document	Publication Date MM-DD-YY	Name of Patentee or Applicant of Cited Document	Translation ?
	Country Code / Number / Kind			

OTHER DOCUMENTS (Including Author, Title, Date, Permanent Pages, etc.)	
DS	Cao et al., "Amorphous Hydrocarbon based Thin Films for High-aspect-ratio MEMS Applications," Thin Solid Films, vol. 398/399, pp. 553-559 (2001)
DS	Cao et al., "Microscale Compression Molding of Al with Surface Engineered LIGA Inserts," submitted for publication in June 2003
DS	Cao et al., "Molding of Pb and Zn with Microscale Mold Inserts," presented at the Materials Research Society Meeting, Boston, Massachusetts (December 2002)
DS	Harris, C. et al., "Design and Fabrication of a Cross Flow Micro Heat Exchanger," IEEE J. Microelectromech. Syst., Vol. 9, no. 4, pp. 502-508 (2000)
DS	Stephens, L.S. et al., "A Pin Fin Microheat Sink for Cooling Macroscale Conformal Surfaces Under the Influence of Thrust and Frictional Forces," IEEE J. Microelectromech. Syst., Vol. 10, no. 2, pp. 222-231 (2001)
DS	Weber, L. et al., "Micromolding: a powerful tool for large-scale production of precise microstructures," SPIE Proceeding, Micromachining and Microfabrication Process Technology II, Austin, TX, pp. 156-167 (1996).

EXAMINER SIGNATURE <i>/Dmitry Suhol/ (05/11/2006)</i>	DATE CONSIDERED <i>05/11/2006</i>
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